

Abstract of the Disclosure

0037 A method and an apparatus for detecting contaminating species such as metal particles on a wafer edge from a semiconductor fabrication process are disclosed. In the method, a wafer is suspended and rotated in a container with a volume of solvent at a bottom portion of the container such that only an edge portion of the wafer is exposed to the solvent. After the wafer is turned in the solvent such that the entire edge portion of the wafer has been exposed to the solvent, the solvent may be removed for analyzing in an electronic instrument for detecting the species of contaminating particles. The apparatus further includes a wafer mounting device for supporting the wafer which can be adjusted in height to suit wafers of different diameters.